

2N6449, 2N6450**N-Channel Silicon Junction Field-Effect Transistor****• High Voltage****Absolute maximum ratings at $T_A = 25^\circ\text{C}$**

	2N6449	2N6450
Reverse Gate Source Voltage	– 300 V	– 200 V
Reverse Gate Drain Voltage	– 300 V	– 200 V
Continuous Forward Gate Current	10 mA	10 mA
Continuous Device Power Dissipation	800 mW	800 mW
Power Derating	6.4 mW/ $^\circ\text{C}$	6.4 mW/ $^\circ\text{C}$

At 25°C free air temperature:

Static Electrical Characteristics

		2N6449		2N6450		Unit	Process NJ42	
		Min	Max	Min	Max		Test Conditions	
Gate Source Breakdown Voltage	$V_{(\text{BR})\text{GSS}}$	– 300		– 200		V	$I_G = -10 \mu\text{A}, V_{\text{DS}} = 0\text{V}$	
Gate Reverse Current	I_{GSS}		– 100			nA	$V_{\text{GS}} = -150\text{V}, V_{\text{DS}} = 0\text{V}$	
				– 100		nA	$V_{\text{GS}} = -100\text{V}, V_{\text{DS}} = 0\text{V}$	
			– 100			μA	$V_{\text{GS}} = -150\text{V}, V_{\text{DS}} = 0\text{V}$	$T_A = 150^\circ\text{C}$
				– 100		μA	$V_{\text{GS}} = -100\text{V}, V_{\text{DS}} = 0\text{V}$	$T_A = 150^\circ\text{C}$
		Gate Source Cutoff Voltage	$V_{\text{GS(OFF)}}$	– 2	– 15	V	$V_{\text{DS}} = 30\text{V}, I_D = 4 \text{nA}$	
Drain Saturation Current (Pulsed)	I_{DSS}	2	10	2	10	mA	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	

Dynamic Electrical Characteristics

Common Source Forward Transfer Admittance	Y_{fs}	0.5	3	0.5	3	mS	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	$f = 1 \text{ kHz}$
Common Source Output Conductance	Y_{os}		100		100	μS	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	$f = 1 \text{ kHz}$
Common Source Input Capacitance	C_{iss}		20		20	pF	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	$f = 1 \text{ MHz}$
Common Source Reverse Transfer Capacitance	C_{rss}		2.5		2.5	pF	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	$f = 1 \text{ MHz}$

TO-39 Package
Dimensions in Inches (mm)

Pin Configuration
1 Source, 2 Drain, 3 Gate & Case